Conductive Epoxy Flow Coating

**FeRFA Type 5 System**
DFT = 1.0-1.5mm

**Typical Environment**
- Light Loads: ✔
- Moderate Loads: ✔
- Increased Loads: ✔
- Heavy Loads: ✗

**Suitable for Surfaces**
- Clean concrete without surface sealer
- Prepared concrete and screeds
- Well adhered existing coating, subject to trial.
- Surfaces prepared by hand grinding

**System Properties:**
- Wide range of colours
- Good abrasion resistance
- Earth Leakage Resistance $10^6$ Ω
- Complies with DIN EN 1081
- Good chemical resistance
- Resistant to mechanical loads
- For areas subject to explosion risk
- Tough surface finish

1. Surface preparation by suitable mechanical means.
2. Prime prepared surfaces with dielectric isolation layer e.g. Epoxy ST 100.
3. Apply copper tapes as required.
4. Apply Epoxy Conductive Layer W over copper grid and primed surfaces.
5. Apply final Conductive Epoxy layer of Epoxy HD Color AS.
# Conductive Epoxy Flow Coating

FeRFA Type 5 System  
DFT = 1.0-1.5mm

<table>
<thead>
<tr>
<th>Item</th>
<th>Operation</th>
<th>Material / m²</th>
<th>Price / m²</th>
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</thead>
<tbody>
<tr>
<td>1</td>
<td><strong>Surface Preparation</strong></td>
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<td>The substrate shall be prepared by suitable means to remove all contaminants and weakness to give a clean, sound load-bearing surface. If over coating an existing finish a trial shall be conducted to assess bond.</td>
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<td>2</td>
<td><strong>Priming</strong></td>
<td>0.3 kg/m²</td>
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<td>The prepared surfaces are primed with chosen priming system e.g. Epoxy ST 100 which also acts as a dielectric isolation layer.</td>
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<td>3</td>
<td><strong>Copper Tape Grid</strong></td>
<td>varies</td>
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<td></td>
<td>Apply grid of copper tapes and fix to a suitable earthing point (by a qualified electrician). Ensure at least 2 earthing points are provided and then at least 1 per 100m² of floor.</td>
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<td>4</td>
<td><strong>Carbon Conductive Layer</strong></td>
<td>0.25 kg/m²</td>
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<td>Apply evenly over both the copper grid and primed floor Epoxy Conductive Layer W to allow charge to be dissipated to the copper grid and then earth.</td>
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<td>5</td>
<td><strong>Top Coat</strong></td>
<td>1.4 kg/m²</td>
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<td>Seal the surfaces with a layer of Epoxy HD Color AS at an even layer thickness of 1mm, allow 15 minutes and then work through with a spike roller.</td>
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</table>

**Total**

**Notes:** Application rates and coverage are theoretical and do not allow for surface profile variation, wastage or variation in application technique. In the case of high substrate roughness you should allow for additional levelling material to be used.